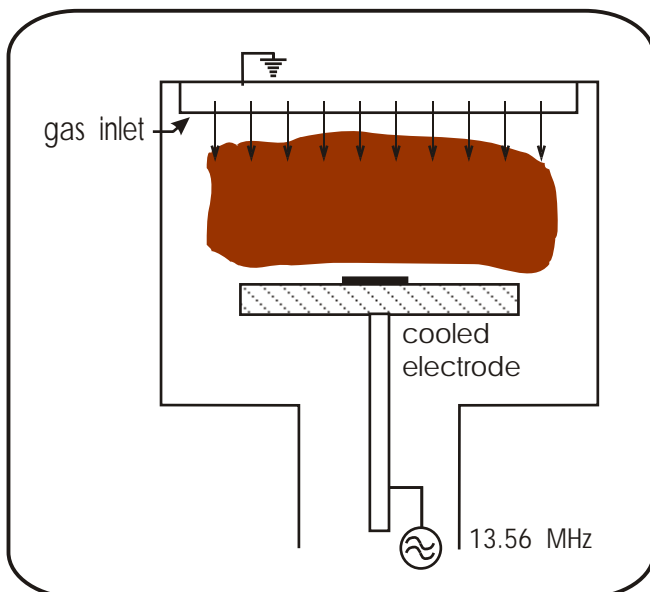
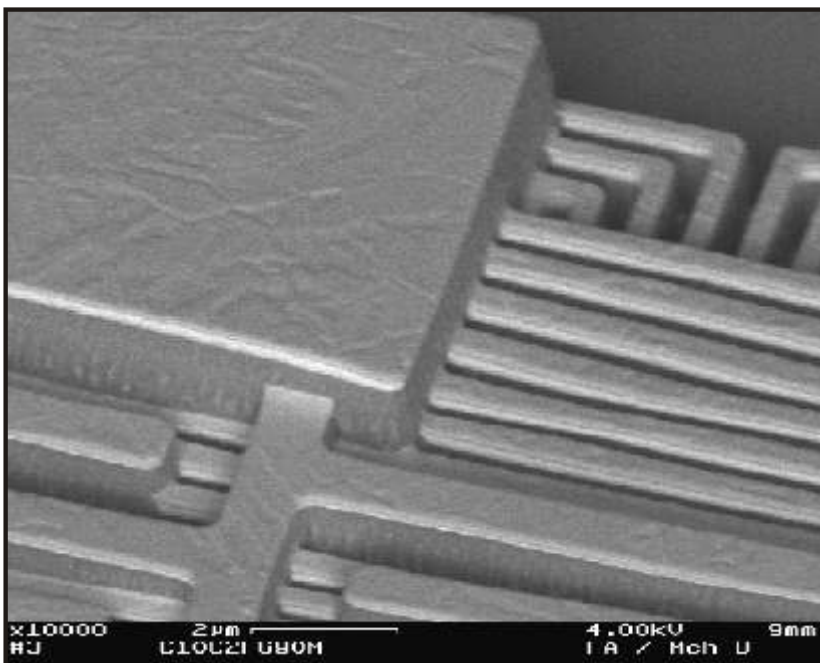


Plasmalab Data

Failure Analysis with Cu Metalisation



Courtesy of Infineon Munich:
0.2 µm Cu technology
etched to M1 - 4

Results:

Anisotropic, smooth etch of SiO₂

Technology:

13 MHz - Plasma
Laser Interferometry
Reactive Ion Etch (RIE)

Equipment:

Plasmalab 80 Plus